Product Information Sheet

EPO-TEK® P1011ST-2

Date: June 2025
Rev: I
No. of Components: Single
Mix Ratio by Weight: N/A
Specific Gravity:
Pot Life: N/A **Dry Time:** 28 Days
Shelf Life- Bulk: Six months at room temperature

Recommended Cure: Pre-Bake: 80°C/30 Minutes (maximum)+
Cure: 150°C/1 Hour (with or without vacuum)+
Post Cure: 285°C/90 Minutes

NOTES:

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.

Product Description: EPO-TEK® P1011S-2 is a single component, modified polyimide, high temperature grade, silver-filled electrically conductive and thermally conductive adhesive designed for semiconducior die-attached and hybrid microelectronic packaging. It is a replacement for EPO-TEK® P1011-ST and a lower-viscosity verison of EPO-TEK® P1011-T2

Typical Properties: Cure condition: Pre-Bake: 80°C/30 Minutes (maximum) - Cure: 150°C/1 Hour (with or without vacuum) – Post-Cure: 285°C/90 Minutes Different batches, conditions & applications yield differing results.
Data below is not guaranteed. To be used as a guide only, not as a specification. * denotes test on lot acceptance basis

PHYSICAL PROPERTIES:		
Color (before cure):	Silver	
Consistency:	Smooth Thixotropic Paste	
Viscosity (23°C) @ 10 rpm:	16,160	cPs
Thixotropic Index:	2.46	
Glass Transition Temp:	Not detected	
Coefficient of Thermal Expansion (CTE):		
Below Tg:		
Above Tg:		
Shore D Hardness:		
Lap Shear @ 23°C:		
Die Shear @ 23°C:		Kg psi
Degradation Temp:		°C
Weight Loss:		
@ 200°C:		%
@ 250°C:		%
@ 300°C:		%
Suggested Operating Temperature:	< 300	°C (Intermittent)
Storage Modulus:		
Particle Size:	≤ 20	microns

ELECTRICAL AND THERMAL PROPERTIES:		
Thermal Conductivity:		W/mK
Volume Resistivity @ 23°C:	< 0.0005	Ohm-cm

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